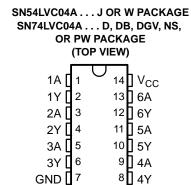
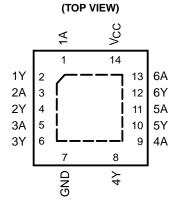


#### **FEATURES**

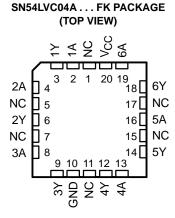
- Operate From 1.65 V to 3.6 V
- Specified From -40°C to 85°C, -40°C to 125°C, and -55°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t<sub>nd</sub> of 4.5 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   >2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C

- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)





SN74LVC04A . . . RGY PACKAGE



NC - No internal connection

#### **DESCRIPTION/ORDERING INFORMATION**

The SN54LVC04A hex inverter contains six independent inverters designed for 2.7-V to 3.6-V  $V_{CC}$  operation, and the SN74LVC04A hex inverter contains six independent inverters designed for 1.65-V to 3.6-V  $V_{CC}$  operation. The 'LVC04A devices perform the Boolean function  $Y = \overline{A}$ .

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### **ORDERING INFORMATION**

T <sub>A</sub>	PA	CKAGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	to 85°C QFN – RGY Reel of 1000		SN74LVC04ARGYR	LC04A
		Tube of 50	SN74LVC04AD	
	SOIC - D	Reel of 2500	SN74LVC04ADR	LVC04A
–40°C to 125°C		Reel of 250	SN74LVC04ADT	
	SOP - NS	Reel of 2000	SN74LVC04ANSR	LVC04A
	SSOP - DB	Reel of 2000	SN74LVC04ADBR	LC04A
		Tube of 90	SN74LVC04APW	
	TSSOP - PW	Reel of 2000	SN74LVC04APWR	LC04A
		Reel of 250	SN74LVC04APWT	
	TVSOP - DGV	Reel of 2000	SN74LVC04ADGVR	LC04A
	CDIP – J	Tube of 25	SNJ54LVC04AJ	SNJ54LVC04AJ
-55°C to 125°C	CFP – W	Tube of 150	SNJ54LVC04AW	SNJ54LVC04AW
	LCCC - FK	Tube of 55	SNJ54LVC04AFK	SNJ54LVC04AFK

<sup>(1)</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (EACH INVERTER)

INPUT A	OUTPUT Y
Н	Г
L	Н

## LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)





# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage range		-0.5	6.5	V	
VI	Input voltage range (2)	Input voltage range <sup>(2)</sup>		6.5	V	
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA	
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA	
Io	Continuous output current			±50	mA	
	Continuous current through V <sub>CC</sub> or GND	Continuous current through V <sub>CC</sub> or GND			mA	
		D package <sup>(4)</sup>		86		
		DB package <sup>(4)</sup>		96	0000	
0	Dealeage the good impedance	DGV package <sup>(4)</sup>		127		
$\theta_{JA}$	Package thermal impedance	NS package <sup>(4)</sup>		76	°C/W	
		PW package <sup>(4)</sup>		113		
		RGY package <sup>(5)</sup>		47		
T <sub>stg</sub>	Storage temperature range		-65	150	°C	
P <sub>tot</sub>	Power dissipation	$T_A = -40$ °C to 125°C <sup>(6)(7)</sup>		500	mW	

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

The package thermal impedance is calculated in accordance with JESD 51-7.

The package thermal impedance is calculated in accordance with JESD 51-5.

For the D package: above 70°C, the value of  $P_{tot}$  derates linearly with 8 mW/K. For the DB, DGV, NS, and PW packages: above 60°C, the value of  $P_{tot}$  derates linearly with 5.5 mW/K.



# Recommended Operating Conditions<sup>(1)</sup>

			SN54LV	C04A	
			–55°C to	125°C	UNIT
			MIN	MAX	
1/	Cumply voltage	Operating	2	3.6	V
V <sub>CC</sub>	Supply voltage	Data retention only	1.5		V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		V
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	V
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
	High lavel autout august	V <sub>CC</sub> = 2.7 V		-12	A
I <sub>OH</sub>	High-level output current	$V_{CC} = 3 V$		-24	mA
1	Low lovel output ourrent	V <sub>CC</sub> = 2.7 V		12	m Λ
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V		24	mA

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# **Recommended Operating Conditions** (1)

					SN74L	VC04A			
			T <sub>A</sub> =	25°C	-40°C	to 85°C	–40°C to 125°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MIN MAX	
M	Cupply valtage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
V <sub>CC</sub>	Supply voltage	Data retention only	1.5		1.5		1.5		V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		1.7		1.7		V
	input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		2		2		
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7		0.7		0.7	V
	input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		0.8		0.8	
VI	Input voltage		0	5.5	0	5.5	0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4		-4		-4	
	High-level	V <sub>CC</sub> = 2.3 V		-8		-8		-8	0
I <sub>OH</sub>	output current	V <sub>CC</sub> = 2.7 V		-12		-12		-12	mA
		V <sub>CC</sub> = 3 V		-24		-24		-24	
		V <sub>CC</sub> = 1.65 V		4		4		4	
	Low-level	V <sub>CC</sub> = 2.3 V		8		8		8	0
I <sub>OL</sub>	output current	V <sub>CC</sub> = 2.7 V		12		12		12	mA
		V <sub>CC</sub> = 3 V		24		24		24	

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

			SN54LVC04A		
PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	–55°C to 125°C	UNIT	
			MIN MAX		
	$I_{OH} = -100 \mu A$	2.7 V to 3.6 V	V <sub>CC</sub> - 0.2		
$V_{OH}$	L = 12 mA	2.7 V	2.2	V	
	$I_{OH} = -12 \text{ mA}$	3 V	2.4		
	$I_{OH} = -24 \text{ mA}$	3 V	2.2		
	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V	0.2		
V <sub>OL</sub>	I <sub>OL</sub> = 12 mA	2.7 V	0.4	V	
	I <sub>OL</sub> = 24 mA	3 V	0.55		
I <sub>I</sub>	$V_I = 5.5 \text{ V or GND}$	3.6 V	±5	μΑ	
I <sub>cc</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	10	μΑ	
$\Delta I_{CC}$	One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND	2.7 V to 3.6 V	500	μΑ	

### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

					s	N74LVC04A	\			
PARAMETER	TEST CONDITIONS	$v_{cc}$	$V_{CC}$ $T_A = 25^{\circ}C$				85°C	–40°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	$I_{OH} = -100 \mu A$	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V <sub>CC</sub> - 0.2		$V_{CC} - 0.3$		
V <sub>OH</sub>	$I_{OH} = -4 \text{ mA}$	1.65 V	1.29			1.2		1.05		
	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			1.7		1.55		V
	l – 12 mΔ	2.7 V	2.2			2.2		2.05		V
	$I_{OH} = -12 \text{ mA}$	3 V	2.4			2.4		2.25		
	$I_{OH} = -24 \text{ mA}$	3 V	2.3			2.2		2		
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.1		0.2		0.3	
	I <sub>OL</sub> = 4 mA	1.65 V			0.24		0.45		0.6	V
V <sub>OL</sub>	$I_{OL} = 8 \text{ mA}$	2.3 V			0.3		0.7		0.85	
	I <sub>OL</sub> = 12 mA	2.7 V			0.4		0.4		0.6	
	I <sub>OL</sub> = 24 mA	3 V			0.55		0.55		8.0	
l <sub>l</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V			±1		±5		±20	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			1		10		40	μΑ
Δl <sub>CC</sub>	One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND	2.7 V to 3.6 V			500		500		5000	μΑ
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		5						pF

## **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				SN54LVC	04A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>cc</sub>	–55°C to 1	25°C	UNIT	
	(1141 51)			MIN	MAX		
	۸	V	2.7 V		5.5		
<sup>L</sup> pd	A	, r	3.3 V ± 0.3 V	0.5	4.5	ns	

# SN54LVC04A, SN74LVC04A HEX INVERTERS

SCAS281R-JANUARY 1993-REVISED JULY 2005



## **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

						S	N74LVC	)4A			
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>cc</sub>	T,	= 25°C		–40°C to	85°C	–40°C to	125°C	UNIT
	( 01)	(0011 01)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
		<b>Y</b>	1.8 V ± 0.15 V	1	4.1	7.5	1	8	1	9.5	
			2.5 V ± 0.2 V	1	3.6	7	1	7.5	1	9	no
<sup>T</sup> pd	Α	T	2.7 V	1	3	5.3	1	5.5	1	7	ns
			3.3 V ± 0.3 V	1	2.5	4.3	1	4.5	1	6	
t <sub>sk(o)</sub>			3.3 V ± 0.3 V					1		1.5	ns

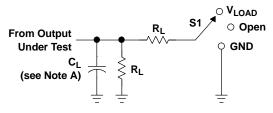
# **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	TYP	UNIT
			1.8 V	6	
$C_{pd}$	Power dissipation capacitance per gate	f = 10 MHz	2.5 V	7	
F-			3.3 V	8	



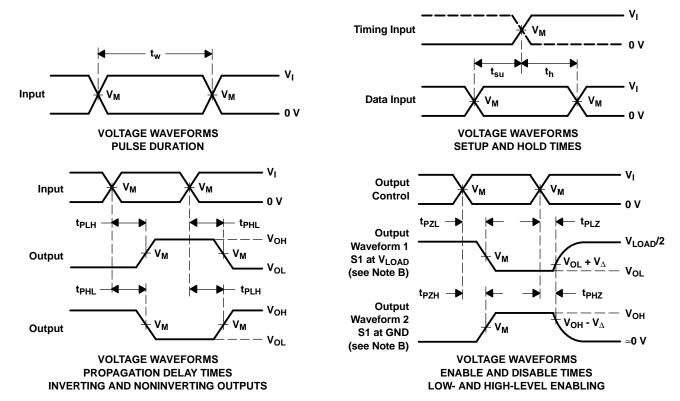
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub> t <sub>PLZ</sub> /t <sub>PZL</sub> t <sub>PHZ</sub> /t <sub>PZH</sub>	Open V <sub>LOAD</sub> GND

**LOAD CIRCUIT** 

.,	INF	PUTS	.,	.,		_	.,
V <sub>CC</sub>	V <sub>I</sub>	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$oldsymbol{V}_\Delta$
1.8 V ± 0.15 V	v <sub>cc</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \ \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9760501Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9760501QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9760501QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN74LVC04AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LVC04ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LVC04ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ADTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LVC04APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)		Level-1-260C-UNLIM
SN74LVC04APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC04ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR



#### PACKAGE OPTION ADDENDUM

26-Sep-2005

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ54LVC04AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LVC04AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LVC04AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## DGV (R-PDSO-G\*\*)

#### **24 PINS SHOWN**

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

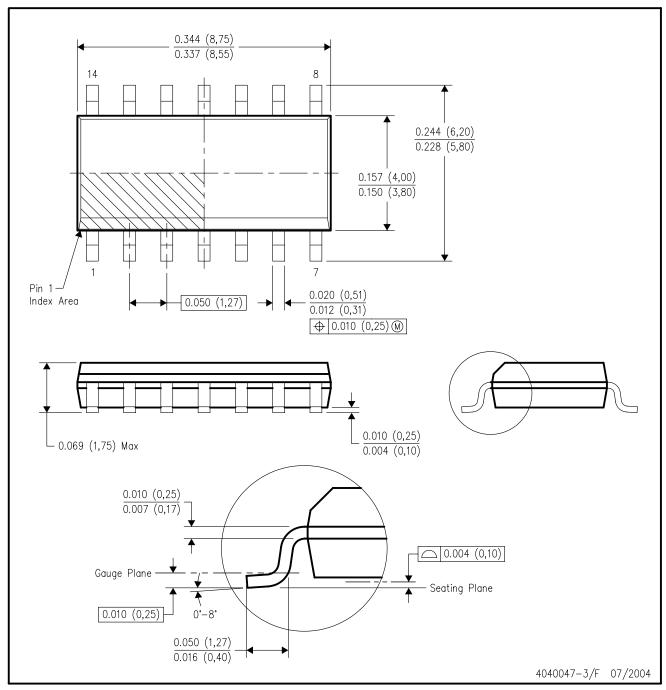
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

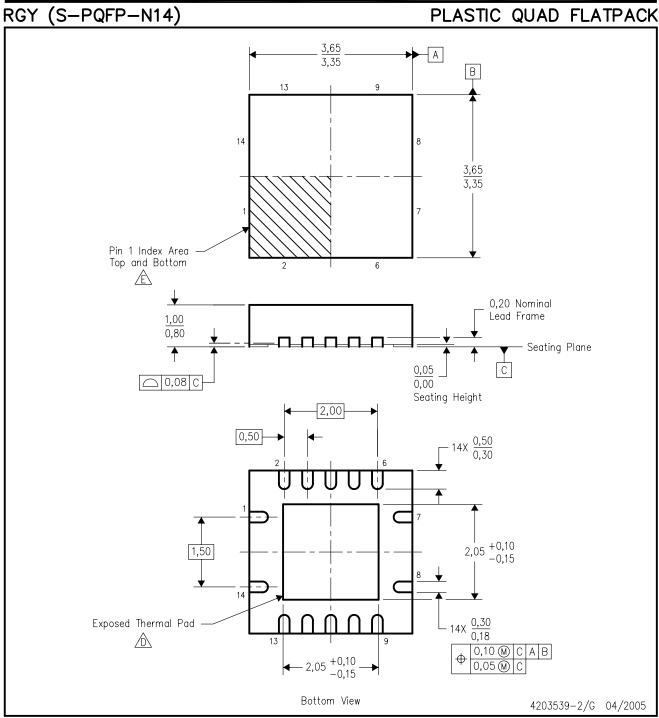
# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.

Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

F. Package complies to JEDEC MO-241 variation BA.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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